

Hack the Plains 2027 Sponsorship

January 22-24, 2027 | Auburn University | Hosted by the AU Mesh Club

A weekend hardware hackathon. Sixty Auburn engineering students spend Friday evening through Sunday noon designing, soldering, and debugging hardware, then demo what they built. Sponsors fund the parts and spend the weekend working next to the students.

Format	Student-built hardware hackathon, Friday 5 PM to Sunday noon
Venue	Brown-Kopel Engineering Student Achievement Center, in partnership with the Auburn Makerspace
Audience	60 students across engineering, mostly computer and electrical engineering, computer science, and software engineering
Hosts	AU Mesh Club with the Auburn IEEE chapter

What you get

Benefit	Bronze	Silver	Gold	Title
	\$250	\$750	\$2,000	\$4,000
Logo on the event website and venue signage	✓	✓	✓	✓
Named in the opening and closing ceremonies	✓	✓	✓	✓
Logo on the event t-shirt	—	✓	✓	✓
Recruiting table on site all day Sunday	—	✓	✓	✓
Resume book from participating students	—	✓	✓	✓
Swag or literature in every hacker bag	—	✓	✓	✓
Named award for a technical goal you set	—	—	✓	✓
30-minute workshop or technical talk	—	—	✓	✓
Seat on the judging panel	—	—	✓	✓
Named in the event title and all press	—	—	—	✓
Opening keynote slot	—	—	—	✓
Top billing on every surface, one sponsor only	—	—	—	✓

The event is student-led. Teams pick their own projects, so sponsor awards are written as goals to hit, such as best use of a given board or radio, rather than as assigned builds.

What we get

Sponsorship goes straight into the event. The club takes no cut and spends nothing on overhead.

- **Hardware.** Microcontrollers, sensors, radios, and the consumables sixty students burn through in a weekend.
- **Food.** Five meals and overnight coffee, since teams stay in the building overnight.
- **Prizes.** The award budget for the general competition and the named sponsor awards.
- **Operations.** Makerspace staffing for after-hours access, printing, signage, and shirts.

In-kind sponsorship

In-kind support counts toward a tier at fair market value, and for a hardware event it is often worth more to us than cash.

- Development boards, modules, and sensors
- 3D printing filament
- Cloud credits and API access
- Test equipment on loan for the weekend
- Catering, or engineers willing to mentor for a few hours

Tell us what you have and we will match it to a tier.

Sponsorship is open for the 2027 event.

Pick a tier and we will send a one-page agreement.

Andrew Suggs, AU Mesh Club

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